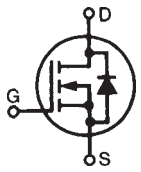
IXYS

Polar2™ HiperFET™ Power MOSFET

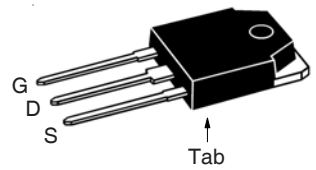
IXFQ24N50P2

V_{DSS} = 500V
I_{D25} = 24A
$R_{DS(on)}$ ≤ 270mΩ

N-Channel Enhancement Mode
Avalanche Rated
Fast Intrinsic Diode



TO-3P



G = Gate D = Drain
S = Source Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 150°C	500	V
V_{DGR}	T_J = 25°C to 150°C, R_{GS} = 1MΩ	500	V
V_{GSS}	Continuous	± 30	V
V_{GSM}	Transient	± 40	V
I_{D25}	T_C = 25°C	24	A
I_{DM}	T_C = 25°C, Pulse Width Limited by T_{JM}	50	A
I_A	T_C = 25°C	12	A
E_{AS}	T_C = 25°C	750	mJ
dv/dt	$I_S \le I_{DM}$, $V_{DD} \le V_{DSS}$, $T_J \le 150°C$	15	V/ns
P_D	T_C = 25°C	480	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	Maximum Lead Temperature for Soldering	300	°C
T_{SOLD}	Plastic Body for 10s	260	°C
M_d	Mounting Torque	1.13/10	Nm/lb.in.
Weight		5.5	g

Features

- Fast Intrinsic Diode
- Dynamic dv/dt Rating
- Avalanche Rated
- Low $R_{DS(ON)}$ and Q_G
- Low Package Inductance

Advantages

- High Power Density
- Easy to Mount
- Space Savings

Applications

- Switch-Mode and Resonant-Mode Power Supplies
- DC-DC Converters
- Battery Chargers
- Uninterrupted Power Supplies
- AC and DC Motor Drives
- High Speed Power Switching Application

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = 250μA	500			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 1mA	2.5		4.5	V
I_{GSS}	V_{GS} = ± 30V, V_{DS} = 0V			± 100	nA
I_{DSS}	$V_{DS} = V_{DSS}$, V_{GS} = 0V			25	μA
	T_J = 125°C			1	mA
$R_{DS(on)}$	V_{GS} = 10V, $I_D = 0.5 \bullet I_{D25}$, Note 1			270	mΩ

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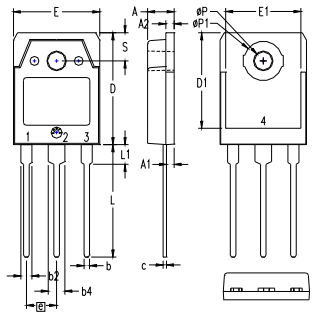
Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS} = 20V, I_D = 0.5 • I_{D25}, Note 1	14	24		S
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		2890		pF
C_{oss}			280		pF
C_{rss}			22		pF
$t_{d(on)}$	**Resistive Switching Times**		15		ns
t_r	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		9		ns
$t_{d(off)}$	R_G = 10Ω (External)		30		ns
t_f			5		ns
$Q_{g(on)}$	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		48		nC
Q_{gs}			13		nC
Q_{gd}			16		nC
R_{thJC}				0.26	°C/W
R_{thCS}			0.25		°C/W

Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0V			24	A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}			96	A
V_{SD}	I_F = I_S, V_{GS} = 0V, Note 1			1.3	V
t_{rr}	I_F = 12A, -di/dt = 100A/μs			200	ns
I_{RM}	V_R = 100V, V_{GS} = 0V		10		A
Q_{RM}			0.69		μC

Note 1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.

TO-3P (IXFQ) Outline



1 – GATE
2 – DRAIN (COLLECTOR)
3 – SOURCE (EMITTER)
4 – DRAIN (COLLECTOR)

SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.185	.193	4.70	4.90
A1	.051	.059	1.30	1.50
A2	.057	.065	1.45	1.65
b	.035	.045	0.90	1.15
b2	.075	.087	1.90	2.20
b4	.114	.126	2.90	3.20
c	.022	.031	0.55	0.80
D	.780	.799	19.80	20.30
D1	.665	.677	16.90	17.20
E	.610	.622	15.50	15.80
E1	.531	.539	13.50	13.70
e	.215 BSC		5.45 BSC	
L	.779	.795	19.80	20.20
L1	.134	.142	3.40	3.60
øP	.126	.134	3.20	3.40
øP1	.272	.280	6.90	7.10
S	.193	.201	4.90	5.10

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,850,072 4,881,106 4,931,844 5,017,508 5,034,796 5,049,961 5,063,307 5,187,117 5,237,481 5,381,025 5,486,715 6,162,665 6,259,123 B1 6,306,728 B1 6,404,065 B1 6,534,343 6,583,505 6,683,344 6,710,405 B2 6,710,463 6,727,585 6,759,692 6,771,478 B2 7,005,734 B2 7,063,975 B2 7,071,537 7,157,338B2

Fig. 1. Output Characteristics @ T_J = 25ºC

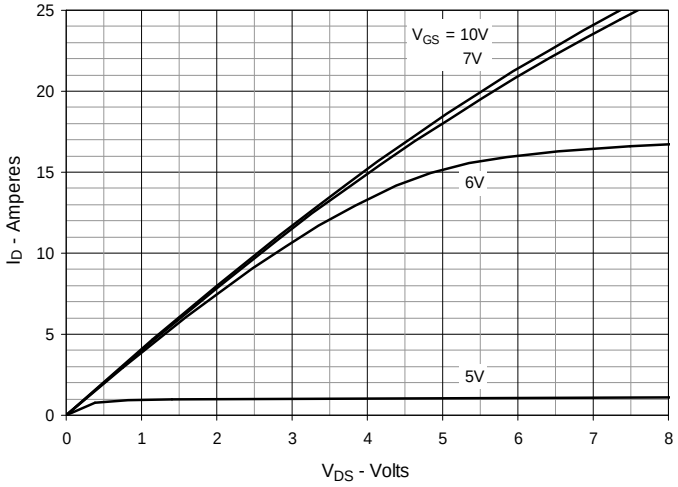


Fig. 2. Extended Output Characteristics @ T_J = 25ºC

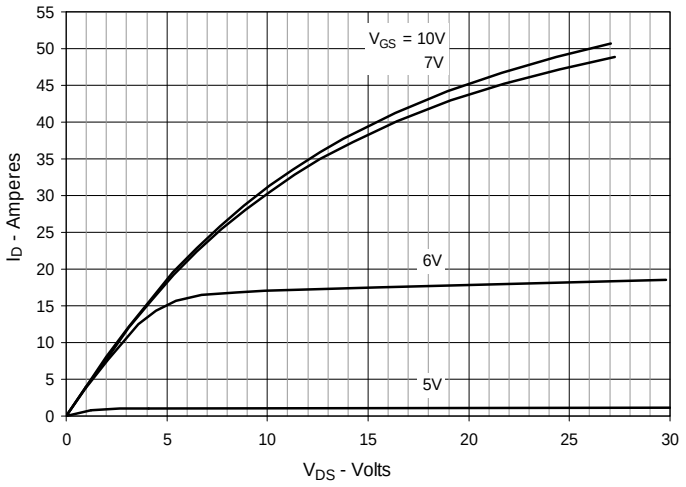


Fig. 3. Output Characteristics @ T_J = 125ºC

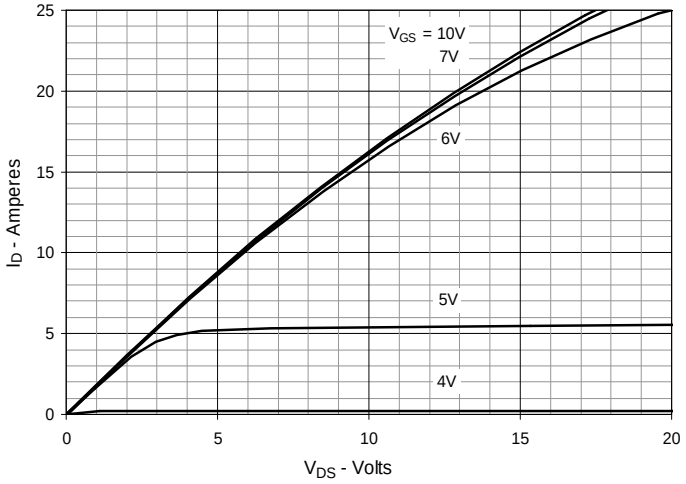


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 12A Value vs. Junction Temperature

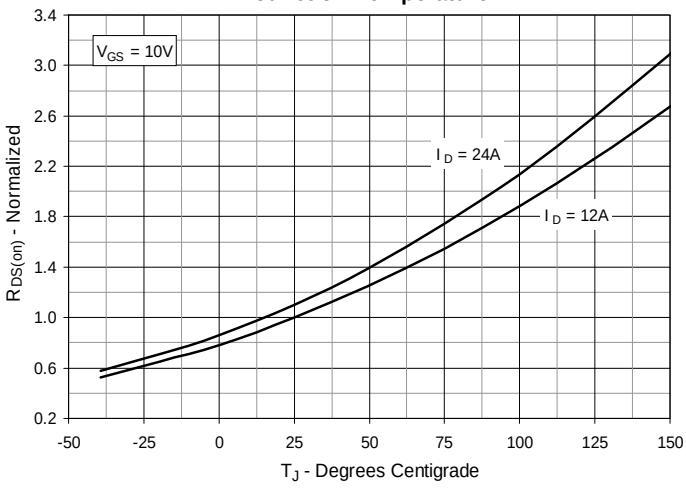


Fig. 5. $R_{DS(on)}$ Normalized to I_D = 12A Value vs. Drain Current

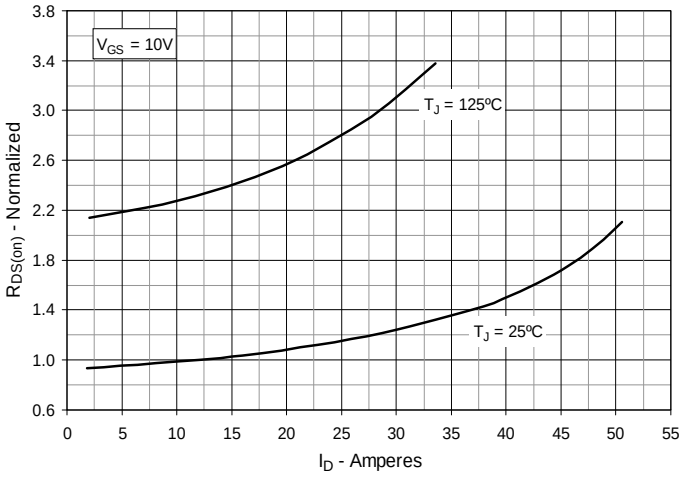
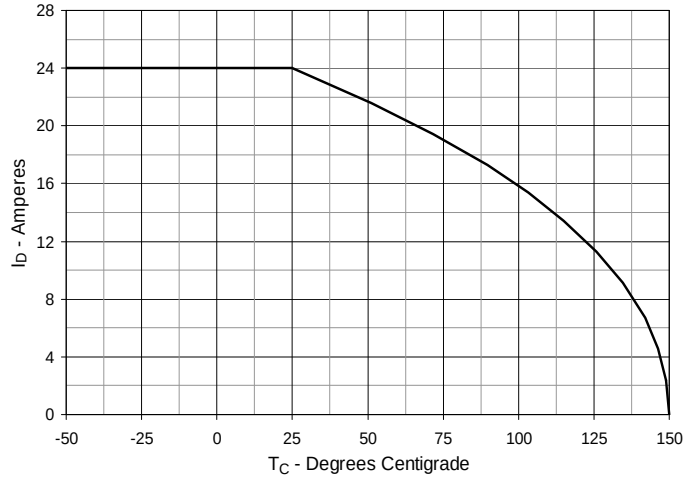


Fig. 6. Maximum Drain Current vs. Case Temperature



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Fig. 7. Input Admittance

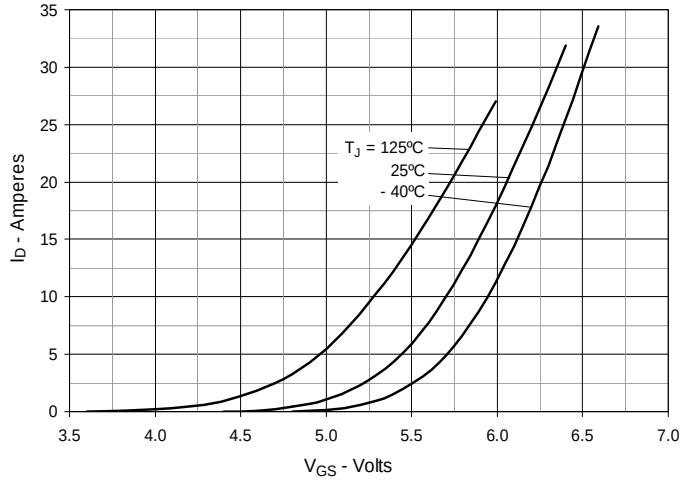


Fig. 8. Transconductance

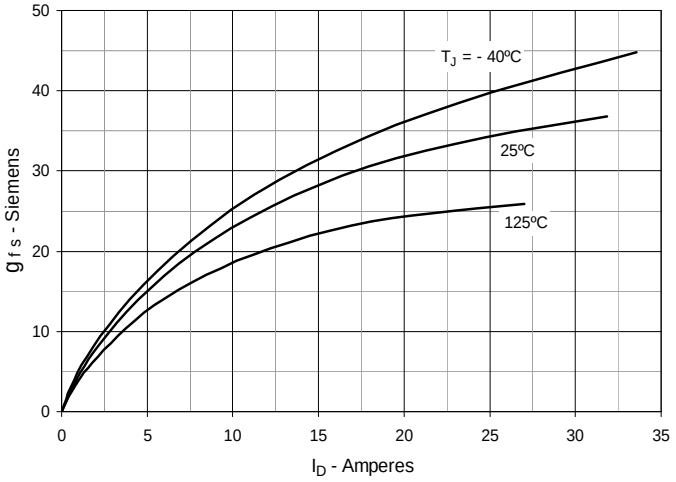


Fig. 9. Forward Voltage Drop of Intrinsic Diode

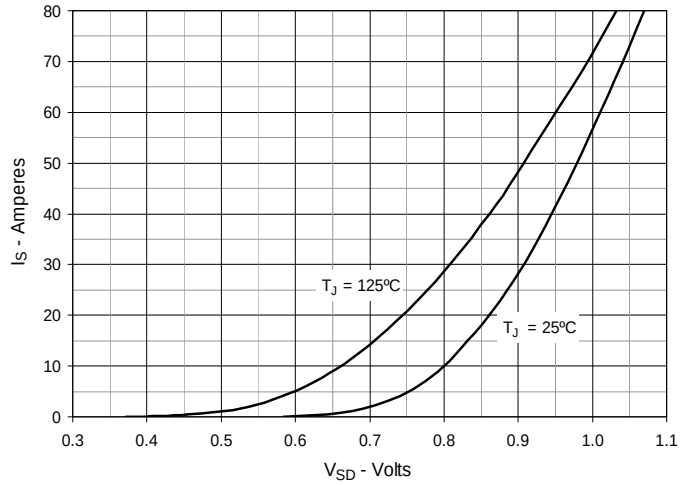


Fig. 10. Gate Charge

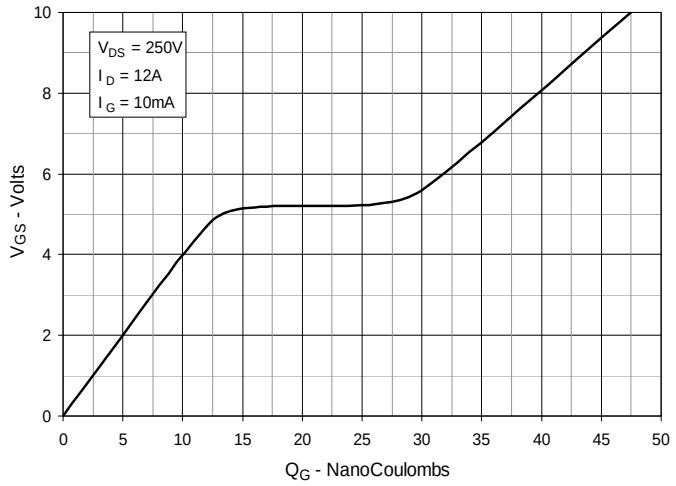


Fig. 11. Capacitance

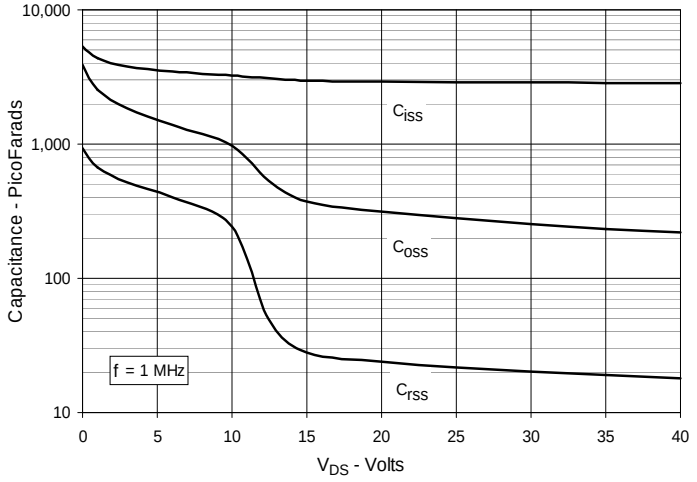
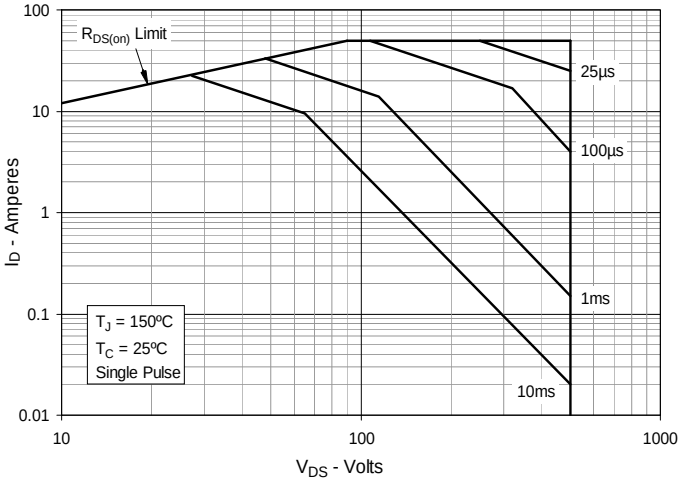
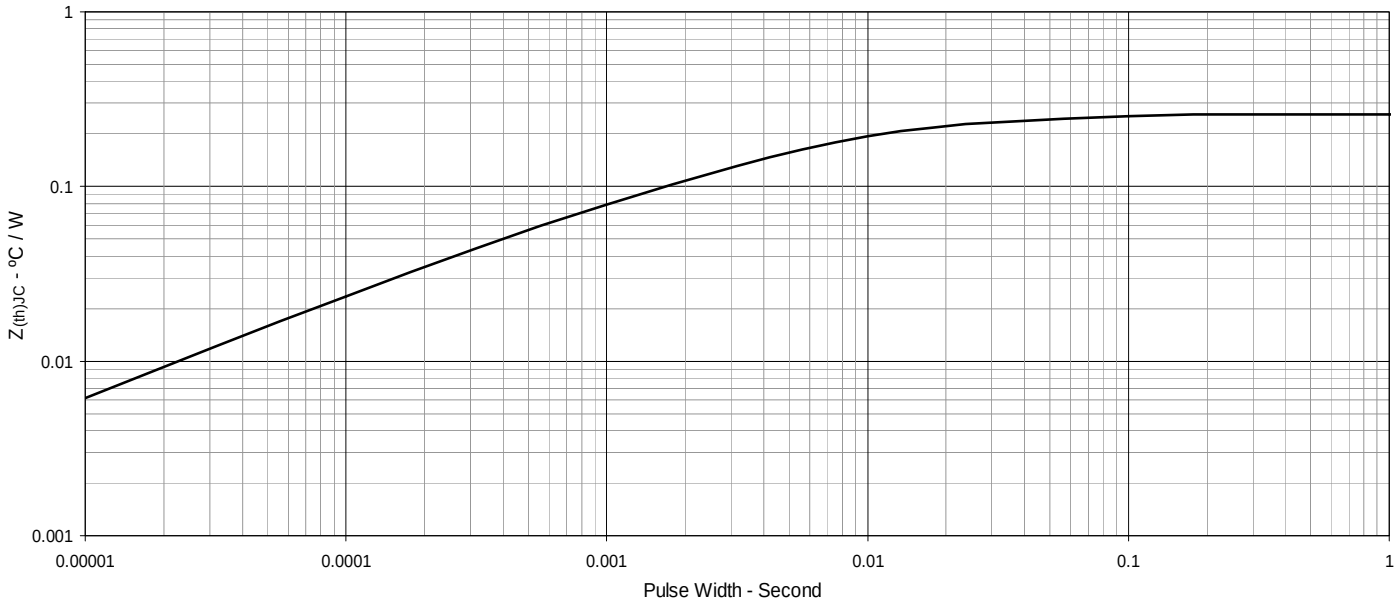


Fig. 12. Forward-Bias Safe Operating Area



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Fig. 13. Maximum Transient Thermal Impedance



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